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PATENT APPLICATION

ATTORNEY DOCKET NO. **1016-013**

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1017 U.S. PTO

09/848997



05/04/01

IN THE U.S. PATENT AND TRADEMARK OFFICE
Patent Application Transmittal Letter

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Sir:

Transmitted herewith for filing under 37 CFR 1.53 (b) is a:

- (X) Utility () Design
- (X) original patent application
- () continuation-in-part application

INVENTOR(S): Lup San Leong

TITLE: THERMAL MECHANICAL PLANARIZATION IN INTEGRATED CIRCUITS

Enclosed are:

- (X) Declaration and Power of Attorney (X) signed () unsigned or partially signed
- (X) 2 sheets of drawings (one set) () Associate Power of Attorney
- () Information Disclosure Statement and Form PTO-1449 with Cited References
- (X) Assignment (X) Recordation Form Cover Sheet (with duplicate copy)
- (X) Priority Document(s)
- () Statement Claiming Small Entity Status
- (X) Acknowledgement Postcard

The filing fee has been calculated as shown below:

(1) FOR	(2) NO. FILED	(3) NO. EXTRA	(4) RATE	(5) AMOUNT
TOTAL CLAIMS	20	minus 20	0	\$ 18.00
INDEPENDENT CLAIMS	3	minus 3	0	\$ 80.00
MULTIPLE DEPENDENT CLAIM(S)				\$ 270.00
BASIC FEE: [X] Utility; [] Design				\$ 710.00
Total of above calculations				\$ 710.00
Assignment Recordation Fee				\$ 40.00
TOTAL FEE				\$750.00

Charge \$750.00 to Deposit Account 50-0374. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-0374 pursuant to CFR 1.25. Additionally please charge any fees to Deposit Account 50-0374 under 37 CFR 1.16, 1.17, 1.19, 1.20, and 1.21. A duplicate copy of this sheet is enclosed.

Correspondence Address:

Respectfully Submitted,

CUSTOMER NO. 22898



Mikio Ishimaru
Registration No. 27,449

Date: May 4, 2001